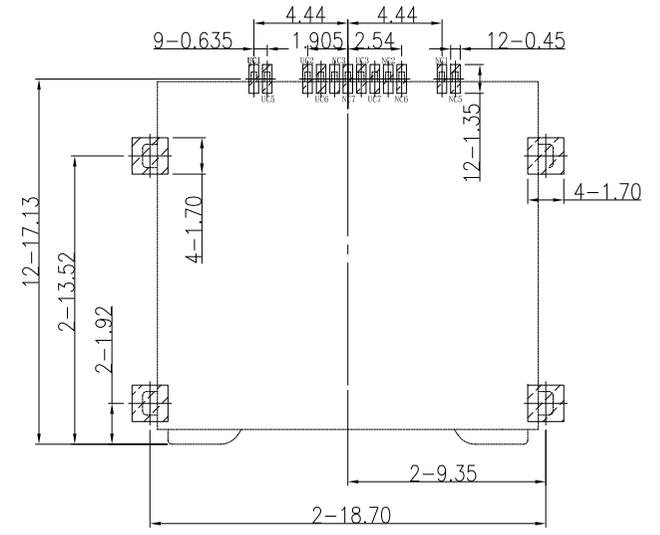
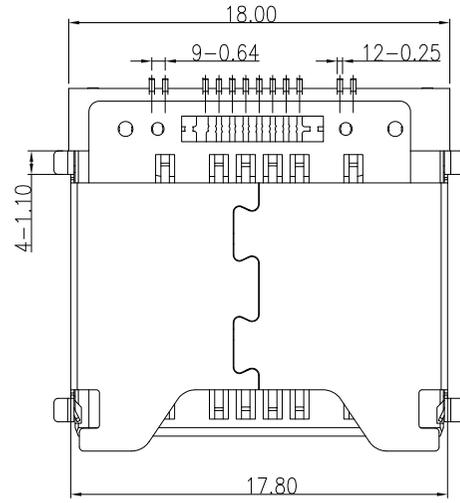
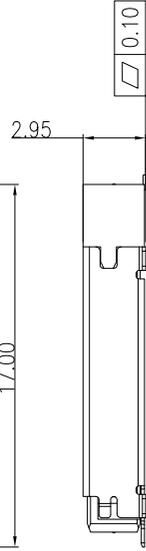
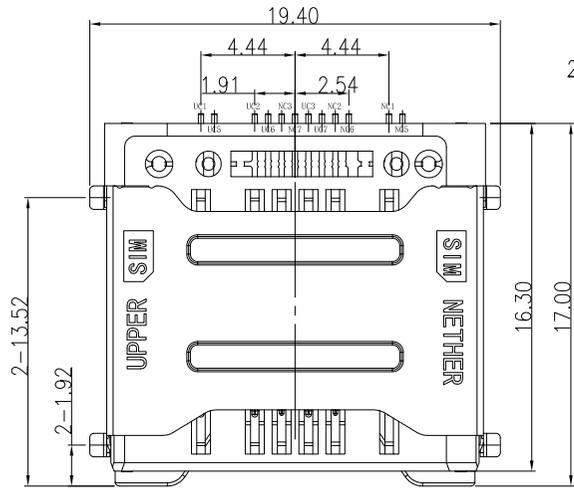
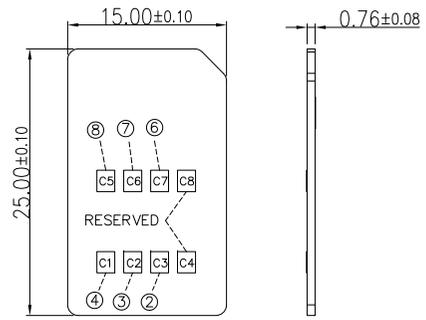
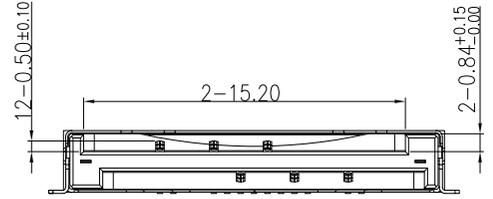


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2023/11/03	Hanson



RECOMMENDED PCB LAYOUT
 TOLERANCE: ± 0.05
 SMT SOLDER AREA



MATRIX PART NO:
MSM-02-01-12-30-98
 Matrix SIM
 01: Push
 02: Non-Push
 Plating
 01:G/F
 Series Number
 Height
 Pin number
 12:12Pin

- Notes:
- Material:
 Housing: High Temperature Thermoplastic (LCP , UL94V-0)
 Terminal:Copper Alloy
 Shell: Stainless Steel
 - Plating:
 Terminal:50u" Ni Underplated Overall
 G/F Plated On Contact Area
 G/F Plated On Solder Area
 Shell:30u" Ni Underplated Overall
 G/F Plated On Solder Area
 - Technical Speciality:
 Rated Voltage: 30V
 Current Rating: 0.5A
 Insulation Resistance:1000M Ω Min.
 Contact Resistance:100m Ω Max.
 Withstanding Voltage: 500V DC For 1 Minutes.
 Operating Temperature: -40C~+85C Humidity 95% R.H Max.

PIN/NO ASSIGNMENT		
④	UC1/NC1	VCC
③	UC2/NC2	RST
②	UC3/NC3	CLK
⑧	UC5/NC5	GND
⑦	UC6/NC6	VPP
⑥	UC7/NC7	I/O



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.38 X.XX ±0.25 X.XXX ±0.15 ANGLE: $\pm 5^\circ$	DESIGN BY : Hanson Huang	DATE : 2023/11/03	PART NAME: Non-Push 双层SIM卡座	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Ray Hsieh	DATE : 2023/11/03	PART NO.	MSM-02-01-12-30-98
	APPROVED BY1: Richard Hsieh	DATE : 2023/11/03	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2023/11/03	DRAW NO.	
			SHEET NO.	1 OF 1